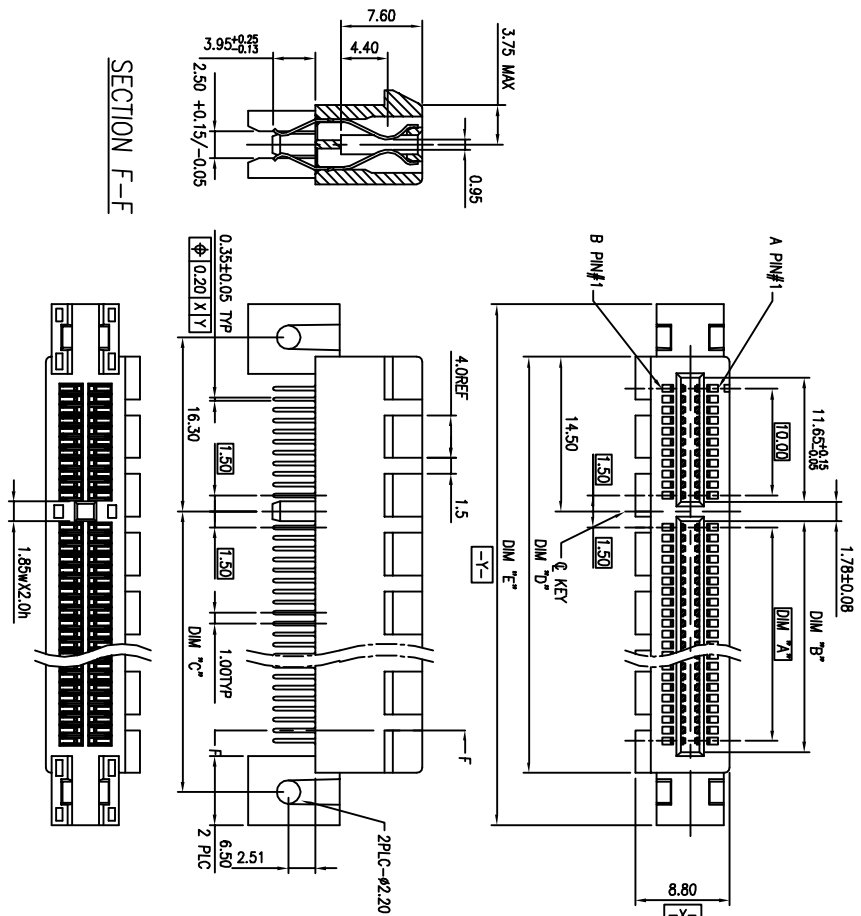




DIMENSIONS					
POSITION	A ± 0.20	B ± 0.15	C ± 0.20	D ± 0.23	E ± 0.30
36	6	7.65	12.30	25.00	34.8
64	20	21.65	26.30	39.00	48.8
98	37	38.65	43.30	56.00	65.8
164	70	71.65	76.30	89.00	98.8

DIMENSION "K"		PCB THICKNESS (DIM "J")	
1.60	2.08 MM		
1.90	2.30 MM		

- NOTES:
1. MATERIAL:
1.1 HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0;
1.2 CONTACTS: COPPER ALLOY.
 2. CONTACT FINISH:
SELECTED GOLD PLATING ON CONTACT AREA.
 3. NO TIE BAR PERMITTED FROM CARD EDGE TO LEADING EDGE OF PAD FOR PINS A1 AND PIN No. 7+.
 4. CHAMFER EDGES MUST BE FREE OF CUTTING EDGE.
 5. FREQUENCY & LOCATION AT SUPPLIER DISCRETION. RIDGE MAY BE CONTINUOUS WITH NO BREAKS.
 6. PRODUCT SPEC.: GS-12-233
 7. THE HSG WILL WITHSTAND EXPOSURE TO 260 +/-5C SOLDER BATH TEMP. FOR 5 SEC. IN A REFLOW SOLDER APPLICATION.

PRODUCT NUMBER CODE

10069690 - X 0 X X X 1 F

HOUSING COLOR OPTIONS
0-NATURAL
1-BLACK

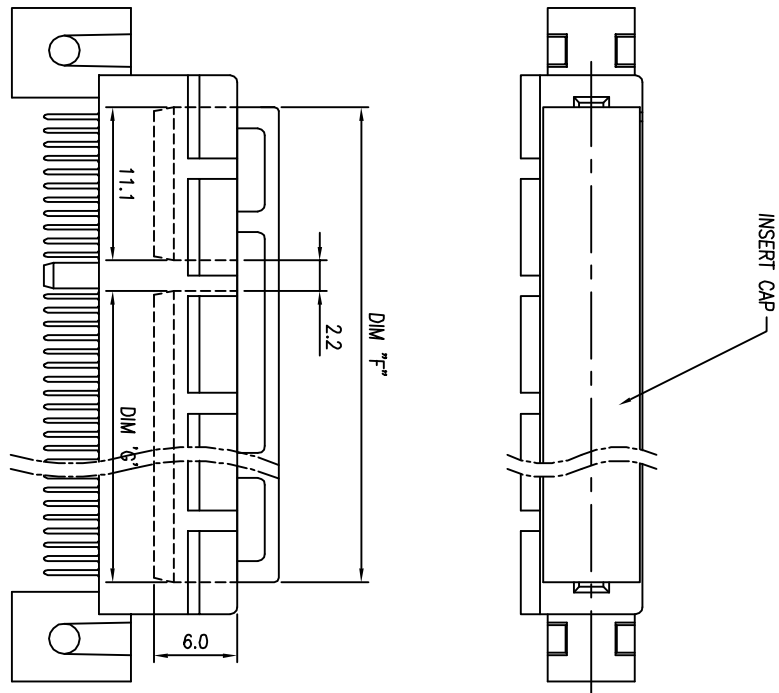
LEAD FREE
PACKAGING OPTIONS
TRAY PACKAGING

POS OPTIONS
0-36
1-64
2-98
3-164

TERMINAL PLATING OPTIONS
0-50U" NI UNDERPLATE
30U" AU CONTACT AREA
100U" MAT TAIL AREA
1-50U" NI UNDERPLATE
150U" AU CONTACT AREA
100U" MAT TAIL AREA
2-50U" NI UNDERPLATE
GOLD FLASH CONTACT AREA
100U" MAT TAIL AREA

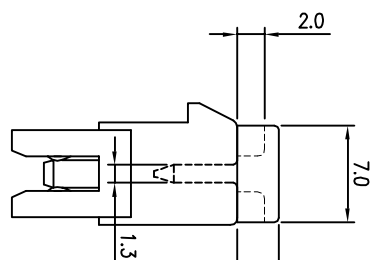
PCB THICKNESS OPTION
0-2.08 MM
1-2.30 MM

mat'l. code		tolerances unless otherwise specified		CUSTOMER COPY		FCI	
lfr	ecn no	dr	date	line	line	projection	title
A	td7-1077	S.L.in	03/13/07		.XX $\pm$ 0.20		PCI EXPRESS
B	td7-1098	S.L.in	06/08/07		.XXX $\pm$ 0.10		STRADDLE MOUNT ASSEMBLY
C	td0-1001	J.H	1/3/08	angles	0° $\pm$ 2°		
		dr	Sterling Lin	05/24/07		MM	product family
		enfr	Sterling Lin	05/24/07			EDGE CARD
		chr	Sterling Lin	05/24/07			size dwg no
		apptd	Minerva Wang	05/24/07			10069690
sheet	revision					scale	code
index	sheet	1	2	3	4	N/A	TWIN
							1 of



DIMENSIONS			
POSITION	F	G	STATUS
36	20.4	7.1	N/A
64	34.4	21.1	N/A
98	51.4	38.1	AVAILABLE
164	84.4	71.1	N/A

- NOTES:
1. MATERIAL:
INSERT CAP: THERMOPLASTIC, HIGH TEMP.,
UL94V-0; BLACK COLOR.
 2. THE INSERT CAP SHALL BE REMOVED OUT
AFTER RE-FLOWED PROCESS.
 3. THIS IS AVAILABLE FOR BX PCI-E ONLY.
P/N: 10069690-XXXX2TLF.



mat'l. code				tolerances unless otherwise specified				CUSTOMER COPY				FCI			
litr	ecn no	dr	date	linear	linear	linear	linear	projection	projection	projection	projection	title	product family	EDGE CARD	code
C					.XX ± 0.20	.XXX ± 0.10	.0" ± 2"					PCI EXPRESS STRADDLE MOUNT ASSEMBLY			
				dr	Sterling Lin	05/24/07									
				engr	Sterling Lin	05/24/07									
				chr	STERLING LIN	05/24/07									
				appd	Minerva Wang	05/24/07									
sheet	revision														
Index	sheet														

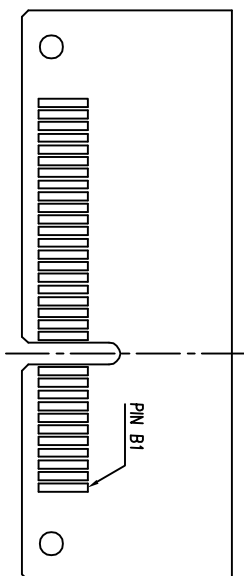
ACAD

1 2

3

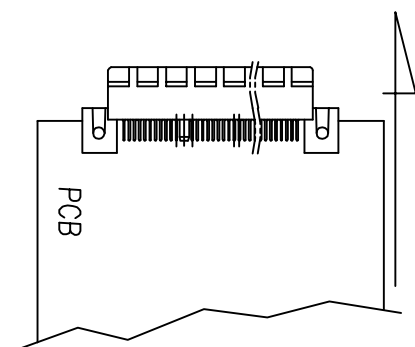
4

code code



RECOMMEND OF REFLOW DIRECTION

# POS REF.	N	DIM "H"
36	6	12.30
64	20	26.30
98	37	43.30
164	70	76.30

[illegible]



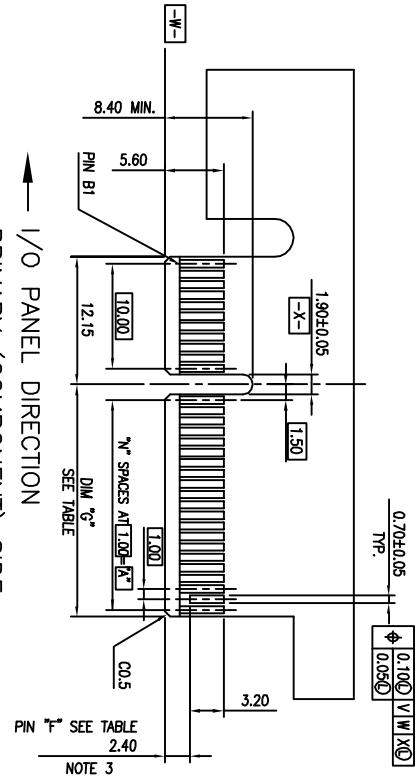
I/O PANEL DIRECTION
SECONDARY (SOLDER) SIDE

# POS REF.	N	DIM "G" ±0.20	"F"
36	6	8.15	B17
64	20	22.15	B31
98	37	39.15	B48
164	70	72.15	B81

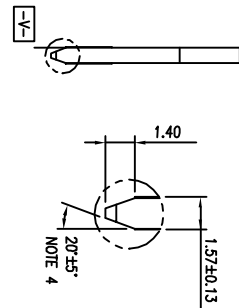
NOTE 3

ADD-IN CARD EDGE-FINGER DIMENSIONS

I/O PANEL DIRECTION
PRIMARY (COMPONENT) SIDE



SCALE 2:1



mat'l. code				tolerances unless otherwise specified				CUSTOMER COPY		FCI		www.fciconnect.com			
lfr	ecn no	dr	date	linear			projection	title	PCI EXPRESS STRADDLE MOUNT ASSEMBLY						
C				.XX ± 0.38 .XX ± 0.25 .XXX ± 0.10				MM	product family	EDGE CARD	code				
				0° ±2°								size	dwg no	TWN	
				angles											
				dr	Sterling Lin 05/24/07										
				engr	Sterling Lin 05/24/07										
				chr	STERLING LIN 05/24/07			scale							
				appr	Minerva Wang 05/24/07			N/A	A4	10069690	sheet	4 of			
sheet	revision														
index	sheet														

ACAD

3

4

cage code